

MICROTRAK DATA SHEET.

Technical data

Dated 01/09/05

Property	Test Method	Specification	Units	Typical Value
	IPC-TM-650 or as noted			
Glass Transition Temperature (Tg) by DSC.Spec Minimum	2.4.25	110-150	°C	150
Decomposition Temperature (Td)	ASTM D3850	-	°C	320
CTE, Z-Axis pre TG	2.4.24	AABUS	ppm/ °C	15
CTE, Z-Axis post TG	2.4.24	-	ppm/ °C	250
CTE, X-, Y-Axis pre TG	2.4.24	AABUS	ppm/ °C	15
CTE, X-, Y-Axis post TG	2.4.24	-	ppm/ °C	17
Thermal Conductivity	ASTM D5930	-	W/mK	0.36
Thermal Stress 10s @ 288°C unetched/ Spec minimum etched	2.4.13.1 2.4.13.1	Pass visual Pass visual	Rating Rating	Pass Pass
Permittivity, A. @ 1MHz Spec maximum B. @ 100 MHz C. @ 1 GHz	2.5.5.3 2.5.5.9 2.5.5.5	5.4 - -	- - -	4.8 4.6 4.5
Loss tangent, A. @ 1MHz Spec maximum B. @ 100 MHz C. @ 1 GHz	2.5.5.3 2.5.5.9 2.5.5.5	0.035 - -	- - -	0.015 0.015 0.015
Volume Resistivity After moisture resistance Spec minimum At elevated temperatures	2.5.17.1 2.5.17.1	10 ⁶ 10 ³	MOhm cm MOhm cm	4.0x 10 ⁸ 7.0x 10 ⁷
Surface Resistivity After moisture resistance Spec minimum At elevated temperatures	2.5.17.1 2.5.17.1	10 ⁴ 10 ³	MOhm MOhm	3.0x 10 ⁶ 6.0x 10 ⁶
Dielectric Breakdown spec minimum	2.5.6	40	kV	60
Arc Resistance spec minimum	2.5.1	60	Seconds	105
Comparative Tracking Index CTI / ASTM D3638	UL-746A	-	Volts	205 (CL=3)
Peel Strength After thermal stress Spec minimum At 125°C After process solutions	2.4.8 2.4.8 2.4.8	105 105 105	N/mm N/mm N/mm	145 145 145
Flexural strength, lengthwise Minimum crosswise	2.4.4 2.4.4	415 345	G.Pa G.pa	442 435
Moisture absorption spec maximum	2.6.2.1	0.80	%	0.20
UL approval	E 45456			
Flammability spec minimum	UL-94	V-1	Rating	V-0
Thickness tolerance dielectric	Class II		mm	1.55 +/- 0.08
Thickness tolerance copper			µm	35 +/- 5
Deformation rel. to diagonal length		< 3	%	<3



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